Amendments to the claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of claims:

Claims 1-15 (canceled)

Claim 16 (new): A heat dissipating structure for a semiconductor package having a substrate, at least a chip mounted on the substrate and electrically connected to the substrate via a plurality of conductive elements, and one or more passive components mounted on the substrate, the heat dissipating structure comprising:

a flat portion; and

a plurality of support portions formed at edges of the flat portion for supporting the flat portion in position above the chip, wherein the support portions are mounted at a predetermined area on the substrate and free of interference with an arrangement of the chip, the passive components and the conductive elements, and the support portions are arranged to form a space between two adjacent support portions, the space being sufficiently dimensioned to accommodate the conductive elements and the passive components so as to allow the conductive elements to pass through the space to reach an area on the substrate outside coverage of the heat dissipating structure and such that the passive components are located within and/or outside the coverage of the heat dissipating structure.

Claim 17 (new): The heat dissipating structure of claim 1, wherein the conductive elements are bonding wires, and a plurality of bond fingers are formed on the substrate for allowing the bonding wires to be bonded to the bond fingers.

Claim 18 (new): The heat dissipating structure of claim 2, wherein the flat portion is elevated above the chip by the support portions and forms a predetermined height difference with respect

to the substrate, allowing the height difference to be larger than a height of wire loops of the bonding wires.

Claim 19 (new): The heat dissipating structure of claim 3, wherein part of the bond fingers are situated on the substrate at an area outside the coverage of the heat dissipating structure, allowing the corresponding bonding wires to pass through the space embraced by adjacent support portions and the flat portion and to reach the outside-coverage bond fingers.

Claim 20 (new): The heat dissipating structure of claim 1, wherein the support portions are situated at edge corners of the flat portion.

Claim 21 (new): The heat dissipating structure of claim 1, wherein the chip and the conductive elements are encapsulated by an encapsulant formed on the substrate.

Claim 22 (new): The heat dissipating structure of claim 6, wherein the flat portion has a top surface exposed to outside of the encapsulant, and a bottom surface opposed to the top surface, the bottom surface being formed with the support portions.

Claim 23 (new): The heat dissipating structure of claim 7, wherein at least a protrusion is formed on the bottom surface of the flat portion and extends toward the chip.

Claim 24 (new): The heat dissipating structure of claim 7, wherein at least a peripherally-situated recess is formed on the top surface of the flat portion.

Claim 25 (new): The heat dissipating structure of claim 1, wherein each of the support portions is formed with at least a hole for allowing an encapsulating resin used for forming the encapsulant to pass through the hole.

Claim 26 (new): The heat dissipating structure of claim 1, wherein each of the support portions is formed with a contact portion at a position in contact with the substrate.

Claim 27 (new): The heat dissipating structure of claim 11, wherein the contact portion substantially extends laterally with respect to the substrate.

Claim 28 (new): The heat dissipating structure of claim 11, wherein the contact portion is of a triangular, rectangular or semicircular shape.

Claim 29 (new): A heat dissipating structure for a semiconductor package having a plurality of conductive elements and one or more passive components, comprising:

a flat portion having a top surface and a bottom surface opposed to the top surface; and

a plurality of support portions formed at edge corners of the bottom surface of the flat portion, wherein the support portions are arranged to form a space between two adjacent support portions, and the space is sufficiently dimensioned to accommodate the conductive elements and the passive components.

Claim 30 (new): The heat dissipating structure of claim 14, wherein the conductive elements are bonding wires, such that the space is dimensioned to have a predetermined height larger than a height of wire loops of the bonding wires.

Claim 31 (new): The heat dissipating structure of claim 14, wherein at least a protrusion is formed on the bottom surface of the flat portion.

Claim 32 (new): The heat dissipating structure of claim 14, wherein the top surface of the flat portion is exposed to outside of the semiconductor package.

Claim 33 (new): The heat dissipating structure . of claim 17, wherein at least a peripherally-situated recess is formed on the top surface of the flat portion.

Claim 34 (new): The heat dissipating structure of claim 14, wherein each of the support portions is formed with at least a hole for allowing an encapsulating resin used in the semiconductor package to pass through the hole.

Claim 35 (new): The heat dissipating structure of claim 14, wherein each of the support portions has one end attached to the flat portion and the other end formed with a contact portion.

Claim 36 (new): The heat dissipating structure of claim 20, wherein the contact portion substantially extends laterally with respect to the flat portion.

Claim 37 (new): The heat dissipating structure of claim 20, wherein the contact portion is of a triangular, rectangular or semicircular shape.

Claim 38 (new): A heat dissipating structure for a semiconductor package having a plurality of bonding wires and one or more passive components, comprising:

a flat portion having a top surface and a bottom surface opposed to the top surface; and

a plurality of support portions formed at edge corners of the bottom surface of the flat portion, wherein the support portions are arranged to form a space between two adjacent support portions, and the space is dimensioned to have a predetermined height larger than a height of wire loops of the bonding wires and a height of the passive components.

Claim 39 (new): The heat dissipating structure of claim 23, wherein at least a protrusion is formed on the bottom surface of the flat portion.

Claim 40 (new): The heat dissipating structure of claim 23, wherein the top surface of the flat portion is exposed to outside of the semiconductor package.

Claim 41 (new): The heat dissipating structure of claim 25, wherein at least a peripherally-situated recess is formed on the top surface of the flat portion.

Claim 42 (new): The heat dissipating structure of claim 23, wherein each of the support portions is formed with at least a hole for allowing an encapsulating resin used in the semiconductor package to pass through the hole.

Claim 43 (new): The heat dissipating structure of claim 23, wherein each of the support portions has one end attached to the flat portion and the other end formed with a contact portion.

Claim 44 (new): The heat dissipating structure of claim 28, wherein the contact portion substantially extends laterally with respect to the flat portion.

Claim 45 (new): The heat dissipating structure of claim 28, wherein the contact portion is of a triangular, rectangular or semicircular shape.